



(1.00 mm) .0394"

MLE-150-01-G-DV

MLE-120-01-G-DV

CLM-111-02-L-D

CLM-126-02-F-D

CLM, MLE SERIES

RUGGED RELIABLE MICRO SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLM or www.samtec.com?MLE

Insulator Material:

Black LCP

Contact Material:

CLM: Phosphor Bronze

MLE: BeCu

Plating:

CLM: Au or Sn over 50 μ" (1.27 μm) Ni

MLE: Au over 10 μ" (0.25 μm) Ni

Current Rating (CLM/FTM):

2.8 A per pin

(2 pins powered)

Current Rating (MLE/FTM):

2.9 A per pin

(2 pins powered)

Operating Temp Range:

-55 °C to +125 °C

Max Cycles:

CLM: 100 with 10 μ" (0.25 μm) Au

Voltage Rating:

MLE: 310 VAC

Insertion Depth:

CLM: Top Entry = (1.40 mm)

.055" min., Bottom Entry =

(2.41 mm) .095" min.

(Add board thickness for correct post OAL)

MLE: (1.63 mm) .064" to

(3.18 mm) .125" with

(0.38 mm) .015" wiper,

pass-through, or

(2.44 mm) .096" minimum

for bottom entry

Normal Force:

CLM: 40 grams (0.39 N) average

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (02-25)

(0.15 mm) .006" max (26-50)*

*(.004" stencil solution

may be available; contact

IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



CLM

1

NO. PINS PER ROW

02

PLATING OPTION

D

OPTIONS

Mates with:

FTM, FTMH, MW

02 thru 50

—F
= Gold flash on contact,
Matte Tin on tail

—L
= 10 μ" (0.25 μm)
Gold on contact,
Matte Tin on tail

—BE
= Bottom Entry
(Required for bottom entry)

—K
= (3.50 mm) .138" DIA
Polyimide film Pick & Place Pad
(7 positions minimum)

—P
= Pick & Place Pad
(7 positions minimum)

—PA
= Pick & Place Pad with
integral Alignment Pin

—TR
= Tape & Reel Packaging

—FR
= Full Reel Tape & Reel
(must order max. quantity per
reel; contact Samtec for
quantity breaks)

